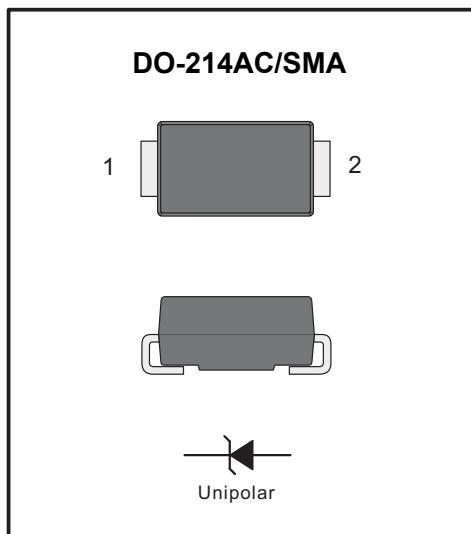


PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

**Features**

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Glass passivated Junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed 250 C/10 seconds at terminals

Mechanical Data

- ◆ **Case :** JEDEC DO-214AC/SMA Molded plastic body
- ◆ **Terminals :** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity :** Polarity symbol marking on body
- ◆ **Mounting Position :** Any
- ◆ **Weight :** 0.0023 ounce, 0.07 grams

Maximum Ratings And Electrical Characteristics

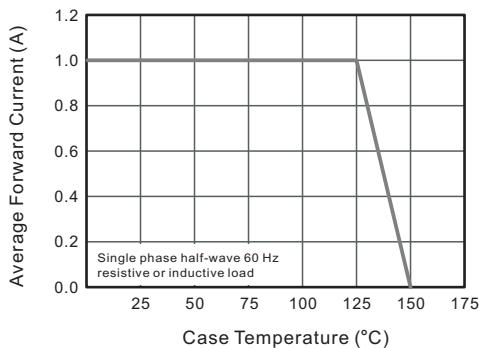
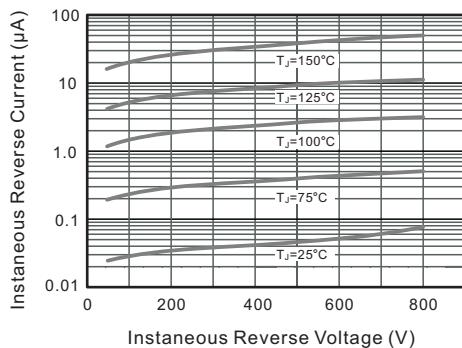
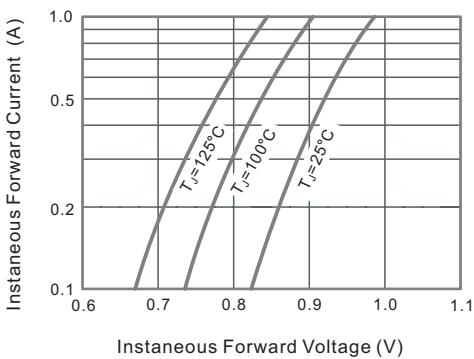
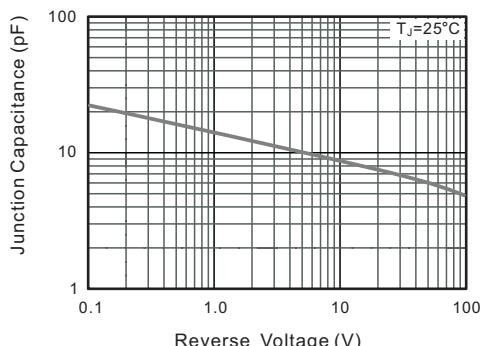
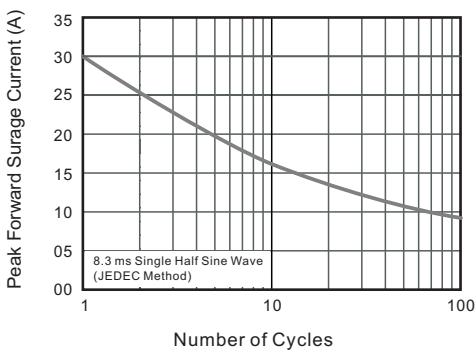
Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	1N4001	1N4002	1N4003	1N4004	1N4005	1N4006	1N4007	UNITS
		M1	M2	M3	M4	M5	M6	M7	
Marking Code									
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at TL=110°C	I _(AV)					1.0			A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}					30			A
Maximum instantaneous forward voltage at 1.0A	V _F				1.1				V
Maximum DC reverse current TA=25°C at rated DC blocking voltage TA=125°C	I _R				5	50			uA
Typical junction capacitance (NOTE 1)	C _J			15.0					pF
Typical thermal resistance (NOTE 2)	R _{θJA}			75.0					°C/W
Operating junction and storage temperature range	T _J , T _{STG}			-55 to +150					°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

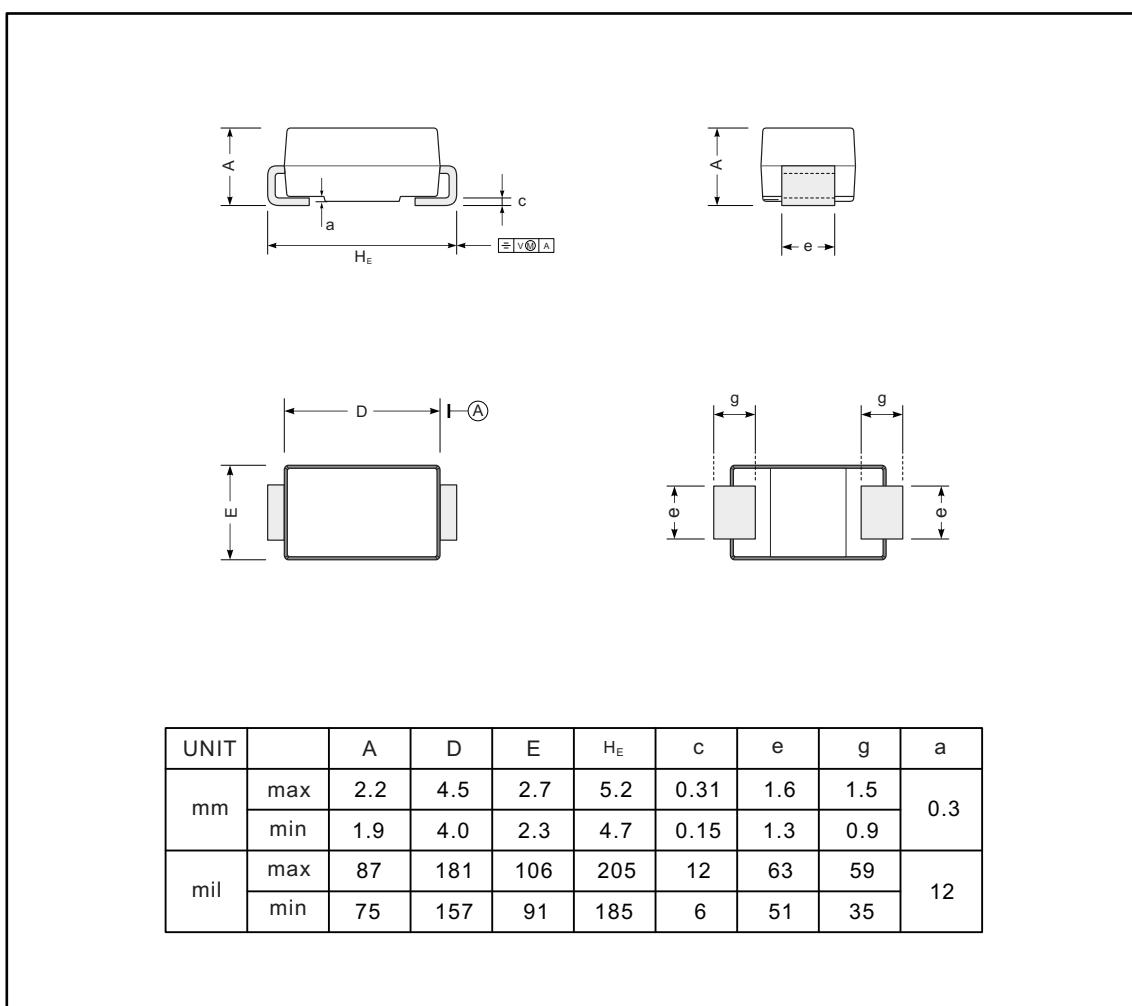
2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

Fig.1 Forward Current Derating Curve**Fig.2 Typical Instantaneous Reverse Characteristics****Fig.3 Typical Forward Characteristic****Fig.4 Typical Junction Capacitance****Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**

PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMA



The recommended mounting pad size

